List of Current Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1 - 29 (Cancelled).

30. (Withdrawn) A circuit board having:

at least one connection bore for receiving a connection wire, or pin, of an electronic component of a predetermined wire, or pin, diameter; and

a holding mechanism in the form of a narrowing in said at least one connection bore to a diameter which is smaller than that of the connection wire, or pin for the purpose of providing a secure holding of the connection wire or pin.

31. (Withdrawn) The circuit board as claimed in claim 30, wherein:

said narrowing is brought about by a foil.

32. (Withdrawn) The circuit board as claimed in claim 31, wherein:

said foil narrowing the cross section of said connection bore is arranged on a surface of the circuit board.

33. (Withdrawn) The circuit board as claimed in claim 31, wherein:

the circuit board is a multi-ply circuit board and that said foil narrowing the cross section of said connection bore is an inner ply of the circuit board.

34. (Withdrawn) The circuit board as claimed in claim 31, wherein:

said foil is slit in the area of said connection bore.

35. (Withdrawn) The circuit board as claimed in claim 31, wherein: said foil is provided with a hole in the area of said connection bore.

36. (Withdrawn) The circuit board as claimed in claim 31, wherein: said foil comprises an electrically conductive material.

37. (Withdrawn) The circuit board as claimed in claim 31, wherein: said foil comprises an insulating, electrically non-conducting material.

38. (New) The circuit board as claimed in claim 30, wherein: said narrowing is brought about by a unilateral bore, which is not completely traversing.

39. (Withdrawn) The circuit board as claimed in claim 30, wherein: said narrowing is brought about by a beaker-shaped shell provided with a restriction and situated in a traversing bore.

40. (Withdrawn) The circuit board as claimed in claim 30, wherein: said narrowing is brought about by two bores.

41. (Withdrawn) The circuit board as claimed in claim 40, wherein: said narrowing is brought about by two equally directed bores having different diameters.

42. (Withdrawn) The circuit board as claimed in claim 40, wherein: said narrowing is brought about by two oppositely directed bores

43. (Withdrawn) The circuit board as claimed in claim 42, wherein: said narrowing is brought about by two oppositely directed bores, which are offset relative to one another.

Claims 44 -49 (Cancelled)

50. (Previously presented) A method for manufacturing a circuit board having at least one connection bore for receiving a connection wire, or pin, of an electronic component of a predetermined wire, or pin, diameter, comprising the steps of:

manufacturing a circuit board with at least one ply, or layer;

drilling a blind hole with a drilling tool having a desired diameter, into the circuit board at a location desired for the connection bore; and

drilling through the floor of the blind hole with a drilling tool having a diameter smaller than the wire, or pin, diameter, in order to form a second bore, so that a narrowing created thereby in the cross section of a part of the connection bore forms a holding mechanism for secure holding of the connection wire, or pin.

51. (Previously presented) A method for manufacturing a circuit board having at least one connection bore for receiving a connection wire, or pin, of an electronic component of a predetermined wire, or pin, diameter, comprising the steps of:

manufacturing a circuit board with at least one ply, or layer;

drilling a first blind hole at a location desired for the connection bore, into the circuit board from a first surface of the circuit board with a drilling tool of a desired diameter; and

drilling a second blind hole from a second surface of the circuit board, into the circuit board, which is arranged slightly offset from the first blind hole and which meets the first blind hole, so that, by the offset of the two blind holes relative to one another, a restriction is formed, which represents a holding mechanism for secure holding of the connection wire, or pin.

52. (Previously presented) A method for manufacturing a circuit board

having at least one connection bore for receiving a connection wire, or pin, of an electronic component of a predetermined wire, or pin, diameter, comprising the steps of:

manufacturing a circuit board with at least one ply, or layer;

drilling a first blind hole, at a location desired for the connection bore, into the circuit board from a first surface of the circuit board with a drilling tool of a desired diameter; and

drilling a second blind bore from a second surface of the circuit board, into the circuit board a second, which is arranged essentially axially parallel and aligned with the first blind hole and which meets the first blind hole but does not extend completely into it, so that, in a portion of the connection bore, where the two blind holes meet one another, a restriction is formed, which represents a holding mechanism for secure holding of the connection wire, or pin.

53. (Withdrawn) The use of a circuit board as claimed in claim 30 with at least one electronic component held in the connection bore by means of the holding mechanism for soldering the component in a reflow soldering oven.

54. (Withdrawn) The use of a circuit board as claimed in claim 53 for a soldering method, in which the component is soldered hanging below the circuit board in a reflow soldering oven.

55. (Withdrawn) The use of a circuit board as claimed in claim 30, with at least one electronic component held in the connection bore by means of a holding mechanism for soldering the component in a wave soldering facility.

Claims 56 - 58 (cancelled)